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## BRAINWARE UNIVERSITY

Term End Examination 2021 - 22

Programme – Diploma in Electronics & Communication Engineering

Course Name – Power Electronics

Course Code - DECE605C

(Semester VI)

Time allotted : 1 Hrs.15 Min.	Full	Marks : 60
[The figure in the margin	indicates full marks.]	
Group	-A	
(Multiple Choice	Type Question)	1 x 60=60
Choose the correct alternative from the following:		
(1) In a three-phase half wave rectifier usually, the prima because	ry side of the transformer is delta connected	
a) it has no neutral connection	b) we can get greater output voltage	
c) it provides a path for the triplen harmonics	d) it provides better temperature stability	
(2) In a three-phase half wave diode rectifier using 3 diod	des, each diode conducts for	
a) 90 degrees	b) 120 degrees	
c) 180 degrees	d) 360 degrees	
(3) In a three-phase half wave 6-pulse mid-point type did	de rectifier, each diode conducts for	
a) 120°	b) 60°	
c) 90°	d) 180°	
(4) A 3-phase bridge rectifier, has the average output voltof line voltage	tage as 286.48 V. Find the maximum value	
a) 100 V	b) 200 V	
c) 300 V	d) 400 V	
(5) In a single pulse semi-converter using two SCRs, the	triggering circuit must produce	
a) two firing pulses in each half cycle	b) one firing pulse in each half cycle	
c) three firing pulses in each cycle	d) one firing pulse in each cycle	
(6) In the complete firing circuit, the driver circuit consis	sts of	
a) pulse generator & power supply	b) gate leads & power supply	
c) pulse amplifier & pulse transformer	d) pulse detector & pulse amplifier	
(7) The magnitude of gate voltage and gate current for tri	iggering an SCR is	
a) inversely proportional to the temperature	b) directly proportional to the temperature	
c) inversely proportional to the anode current require	d) directly proportional to the anode curre	

(8) The major function of the pulse transformer is to

a) increase the voltage amplitude	b) reduce narmomes	Refreet Kate	
c) isolate low & high power circuit	d) create periodic pulses	Barasat, Kalkate -709	
(9) A p-type semiconductor material is doped with impute onductor material is doped with impute	rities	s a n-type semic	
a) acceptor, donor	b) acceptor, acceptor		
c) donor, donor	d) donor, acceptor		
(10) The n-region has a greater concentration of tion diode.	as compared to the p-region in a P-N junc		
a) holes	b) electrons		
c) both holes & electrons	d) phonons		
(11) In the p & n regions of the p-n junction thege carriers respectively.	& the are the	minority char	
a) holes, holes	b) electrons, electrons		
c) holes, electrons	d) electrons, holes		
(12) Which of the following is true in case of an unbiase	d p-n junction diode?		
a) Diffusion does not take place	b) Diffusion of electrons &	holes goes on infinitel	
c) There is zero electrical potential across the junctio	d) Charges establish an electric field across the junions		
(13) An ideal power diode must have			
a) low forward current carrying capacity	b) large reverse breakdown voltage		
c) high ohmic junction resistance	d) high reverse recovery time		
(14) Power diode is			
a) a three terminal semiconductor device	b) a two terminal semiconductor device		
c) a four terminal semiconductor device	d) a three terminal analog device		
(15) Which of the following is true in case of a power dio	de with R load?		
a) I grows almost linearly with V	b) I decays almost linearly with V		
c) I is independent of V	d) I initial grows than decays		
(16) A diode is said to be forward biased when the			
a) cathode is positive with respect to the anode	b) anode is positive with resp	ect to the cathode	
c) anode is negative with respect to the anode	d) both cathode & anode are	positive	
(17) A power diode with small softness factor (S-factor) h	as		
a) small oscillatory over voltages	b) large oscillatory over voltages		
c) large peak reverse current	d) small peak reverse current		
(18) At turn-on the initial delay or turn on delay is the time	e required for the		
<ul> <li>a) input inductance to charge to the threshold value</li> <li>c) input inductance to discharge to the threshold value</li> </ul>	<ul> <li>b) input capacitance to charge to the threshold value</li> <li>d) input capacitance to discharge to the threshold value</li> </ul>		
(19) Choose the correct statement			
a) MOSFET suffers from secondary breakdown problems	b) MOSFET has lower switching losses as compared to other devices		
<ul> <li>MOSFET has high value of on-state resistance as compared to other devices</li> </ul>	d) All of the mentioned		
(20) Which among the following devices is the most suited	for high frequency applications	s?	
a) BJT	b) IGBT		
c) MOSFET	d) SCR		
(21) For a MOSFET Vgs=3V, Idss=5A, and Id=2A. Find th	e pinch of voltage Vp		
a) 4.08	b) 8.16		

	d) 0V	
c) 16.32 (22) The basic advantage of the CMOS technology is that	b) It has small size  Bratraware University	
(22) The basic advantage of the civil	b) It has small size  d) It has better switching capabilities	
a) It is easily available     c) It has lower power consumption	d) It has better switching capabilities	
(23) The MOSFET combines the areas of &	and the second of the second o	
a) field effect & MOS technology	b) semiconductor & TTL	
c) mos technology & CMOS technology	d) none of the mentioned	
(24) The arrow on the symbol of MOSFET indicates		
a) that it is a N-channel MOSFET	b) the direction of electrons	
c) the direction of conventional current flow	d) that it is a P-channel MOSFET	
(25) The controlling parameter in MOSFET is	A Color of the Col	
	b) Ig	
a) Vds	d) Is	
c) Vgs (26) In the internal structure of a MOSFET, a parasitic BJ		
.3 (5)	b) source & drain terminals	
a) source & gate terminals	d) there is no parasitic BJT in MOSFET	
c) drain & gate terminals		
(27) In the transfer characteristics of a MOSFET, the thres	b) minimum voltage till which temperature is consta	
a) minimum voltage to induce a n-channel/p-channel for conduction	nt	
c) minimum voltage to turn off the device	d) none of the above mentioned is true	
(28) The output characteristics of a MOSFET, is a plot of		
a) Id as a function of Vgs with Vds as a parameter	b) Id as a function of Vds with Vgs as a parameter	
c) Ig as a function of Vgs with Vds as a parameter	d) Ig as a function of Vds with Vgs as a parameter	
(29) A power transistor is a		
a) three layer, three junction device	b) three layer, two junction device	
c) two layer, one junction device	d) four layer, three junction device	
(30) A power transistor is a device.		
a) two terminal, bipolar, voltage controlled	b) two terminal, unipolar, current controlled	
c) three terminal, unipolar, voltage controlled	d) three terminal, bipolar, current controlled	
c) three terminal, unipolal, votage commons	The second of the board of the second of the	
(31) In a power transistor, the IB vs VBE curve is	b) an exponentially decaying curve	
a) a parabolic curve	d) a straight line Y = IB	
c) resembling the diode curve	d) a straight line 1 12	
(32) The forward current gain $\alpha$ is given by		
a) IC/IB	b) IC/IE	
c) IF/IC	d) IE/IB	
(33) A power BJT is used as a power control switch by b the saturation region (on state). In the on state	iasing it in the cut off region (off state) or in	
a) both the base-emitter & base-collector junctions a	b) the base-emitter junction is reverse biased, and the base collector junction is forward biased	
re forward biased	d) both the base-collector & the base-emitter junctio	
<ul> <li>c) the base-emitter junction is forward biased, and the e base collector junction is reversed biased</li> </ul>	ns are reversed biased	
(34) The power electronics devices have a very high effi-	ciency because	
a) cooling is very efficient	<ul> <li>b) the devices traverse active region at high speed &amp; stays at the two states, on and off</li> </ul>	
c) the devices never operate in active region	d) the devices always operate in the active region	
(35) High frequency operation of any device is limited b	y the	

<ul> <li>a) forward voltage rating</li> </ul>	b) switching losses			
c) thermal conductivity	d) heat Sink arrangem	LIBICARY		
(36) A 1mv of i/p gives an output of 1V, the vo	oltage gain as such would be	Brainware University		
a) 0.001	b) 0.0001	b) 0.0001  Baresal, Kelium -7001		
c) 1000	d) 100			
(37) IGBT possess				
a) low input impedance	<ul><li>b) high input impedar</li></ul>	nce		
c) high on-state resistance	d) second breakdown	problems		
(38) The three terminals of the IGBT are				
a) base, emitter & collector		b) gate, source & drain		
c) gate, emitter & collector	d) base, source & dra	d) base, source & drain		
(39) The controlling parameter in IGBT is the				
a) IG	b) VGE			
c) IC	d) VCE			
(40) The voltage blocking capability of the IGH	3T is determined by the			
a) injection layer	b) body layer			
c) metal used for the contacts	d) drift layer			
(41) The structure of the IGBT is a				
a) P-N-P structure connected by a MOS gate	e b) N-N-P-P structure	connected by a MOS gate		
c) P-N-P-N structure connected by a MOS g		d) N-P-N-P structure connected by a MOS gate		
(42) When latch-up occurs in an IGBT				
a) Ig is no longer controllable	b) Ic is no longer con	b) Ic is no longer controllable		
c) the device turns off		d) Ic increases to a very high value		
(43) The static V-I curve of an IGBT is plotted				
a) Vce as the parameter	b) Ic as the parameter			
c) Vge as the parameter		d) Ig as the parameter		
(44) The approximate equivalent circuit of an I	•			
a) a BJT & a MOSFET		CT		
c) two BJTs	d) two MOSFETs	b) a MOSFET & a MCT		
(45) The body of an IGBT consists of a	d) two MOSPETS			
a) p-layer	1.			
c) p-n layer	b) n-layer			
	d) metal			
(46) At present, the state-of-the-art semiconduc				
a) Semiconducting Diamond	b) Gallium-Arsenide	b) Gallium-Arsenide		
c) Germanium	d) Silicon-Carbide	d) Silicon-Carbide		
(47) Which terminal does not belong to the SCI	R?			
a) Anode	b) Gate	b) Gate		
c) Base	d) Cathode			
(48) An SCR is a				
a) four layer, four junction device	b) four laws at			
c) four layer, two junction device	d) three leading in the property of the control of	b) four layer, three junction device		
(49) Choose the false statement.	d) three layer, single	junction device		
a) SCR is a bidirectional device				
c) In SCR the gate is the controlling termina		b) SCR is a controlled device		
(50) In the SCR structure 4.	d) SCD are 1 c	high-power applications		
(50) In the SCR structure the gate terminal is lo	cated			

a) near the anode terminal     in between the anode & cathode terminal	b) near the cathode terminal	LIBRARY
(51) The static V-I curve for the SCR is plotted for	d) none of the mentioned	<b>Bratnware University</b>
a) Ia (anode current) vs Ig (gate current), Va (anode	Ы	Beraset, Kolkate -700125
- cathode voltage) as a parameter	b) Ia vs Va with Ig as a parameter	
c) Va vs Ig with Ia as a parameter	d) Ig vs Vg with Ia as a parameter	
(52) If the cathode of an SCR is made positive with respective hen	t to the anode & no gate current	is applied t
a) all the junctions are reversed biased	b) all the junctions are forward biased	
c) only the middle junction is forward biased	d) only the middle junction is reversed biased	
(53) With the anode positive with respect to the cathode & in the	the gate circuit open, the SCR is	s said to be
a) reverse blocking mode	b) reverse conduction mode	
c) forward blocking mode	d) forward conduction mode	
(54) The forward break over voltage is the		
<ul> <li>a) anode-cathode voltage at which conduction starts with gate signal applied</li> </ul>	<ul> <li>b) anode-cathode voltage at which conduction starts with no gate signal applied</li> </ul>	
c) gate voltage at which conduction starts with no an ode-cathode voltage	<ul> <li>d) gate voltage at which conduction starts with anod e-cathode voltage applied</li> </ul>	
(55) For a forward conducting SCR device, as the forward	anode to cathode voltage is inci-	reased
<ul> <li>a) the device turns on at higher values of gate curren</li> <li>t</li> </ul>	b) the device turns on at lower values of gate current	
<ul> <li>c) the forward impedance of the device goes on increasing</li> </ul>	d) the forward impedance of the device goes on decreasing	
(56) A thyristor can be bought from the forward conduction	on mode to forward blocking mo	de by
a) the dv/dt triggering method	b) applying a negative gate si	gnal
c) applying a positive gate signal	d) applying a reverse voltage across anode-cathode t erminals	
57) Usually the forward voltage triggering method is not	used to turn-on the SCR becaus	e
a) it increases losses	b) it causes noise production	
c) it may damage the junction & destroy the device	d) relatively it's an inefficient method	
58) The forward break over voltage is maximum when		
a) Gate current = $\infty$	b) Gate current = 0	
c) Gate current = -∞	d) It is independent of gate current	
59) The value of anode current required to maintain the c ignal is removed is called as the		
a) holding current	b) latching current	
c) switching current	d) peak anode current	
i0) In the reverse blocking mode the middle junction (J2)	) has the characteristics of that	of a
a) transistor	b) capacitor	
c) inductor	d) inductor	
c) madelor	=, madeior	